

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (currently amended): An electroconductive fine particle,
which has a gold coating formed by electroless gold plating on the surface of a nickel undercoating,

the amount of nickel dissolved in a dissolution test of the electroconductive fine particle with nitric acid being 30 to 100 $\mu\text{g/g}$,

wherein the electroconductive fine particle is produced by a method, comprising forming a gold coating wherein a reducing agent, causing oxidation reaction on the surface of a nickel undercoating but not causing oxidation reaction on the surface of gold as deposited metal, is present on the surface of the nickel undercoating, thereby reducing a gold salt to deposit gold.

2. (currently amended): A method of producing the electroconductive fine particle according to Claim 1,

~~wherein the method allows a reducing agent, causing oxidation reaction on the surface of a nickel undercoating but not causing oxidation reaction on the surface of gold as deposited metal, to be present on the surface of the nickel undercoating thereby reduces a gold salt to deposit gold~~
the reducing agent is a sulfite salt.

3. (original): An anisotropic electroconductive material,

which comprises the electroconductive fine particle according to Claim 1 dispersed in a resin binder.